

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	3068	diffusion and S1	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:35
S1	27267	solder near bump	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:35
S5	44	S2 and S3 and S4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
S4	15823	diffusion near coefficient	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
S3	361505	(melting near point) (melting-point) (melting \$1point)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 13:36
S6	1	"10577450".rlan. or ("10". src. and "577450".ap.)	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2008/09/25 14:44
S8	55416	(gold Au) with (bump ball contact)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:49
S7	9033	gold near2 (bump ball)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:49
S12	858	diffusion and S11	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
S11	1843	S8 and S9 and S10	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52

S10	539137	Sn Tin	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
S9	34349	TiW (titanium near tungsten) titanium/tungsten Ti/W	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:52
S14	280	S12 and S13	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:53
S13	365737	melt\$ near point	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:53
S15	20329	(gold Au) with (bump ball)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:54
S16	204	S15 and S9 and S10 and diffusion and (melt\$3 near (point temperature))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 14:55
S17	43	((Au gold) near bump) and S16	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:04
S20	92	S18 and S19	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:10
S19	6553	(gold Au) and (Sn tin) and S9	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/25 15:10
S18	804	(257/781).CCLS.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/25 15:10
S22	1	54-159173	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/01/13 18:53

S24	6836	(gold Au) and (Sn tin) and S23	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:10
S23	35553	TiW (titanium near tungsten) titanium/tungsten Ti/W	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:10
S26	1321	(gold Au) and (Sn tin) and S25	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:11
S25	5611	S23 not ("titanium, tungsten" "tungsten, titanium")	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:11
S28	325	(bump ball) and S27	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:12
S27	762	S26 and @ad<"20040811"	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/13 19:12
S29	2	("20050223986").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/13 19:29
S30	2	("5290588").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/14 13:57
S31	2	("5462638").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/14 14:04
S32	2	("5367195").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/01/15 10:49
L2	83	(semiconductor near chip) same stack\$3 same bump and chip-on-chip	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/15 13:28

L1	972	(semiconductor near chip) same stack\$3 same bump	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/15 13:28
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1/15/2009 2:06:58 PM

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